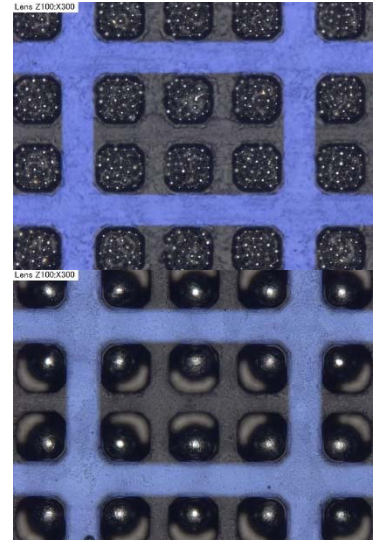
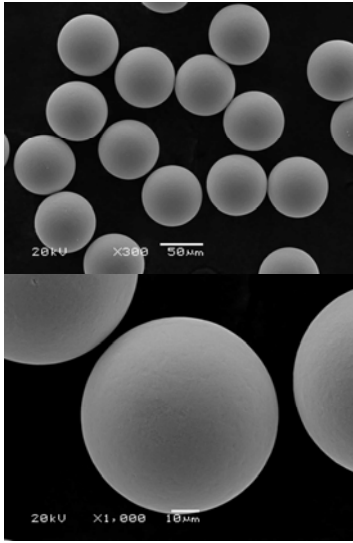


SHENMAO Exhibits at SEMICON TAIWAN on September 7-9, 2016
Booth # J2922 Featuring BGA Solder Spheres and Bumping Paste



SHENMAO BGA Solder Spheres for PBGA, CBGA, TBGA, MBGA, CSP and Flip Chip Assemblies are made by UMT (Ultra Micron Technology) from highly pure metals produced to various exact Alloy compositions using Piezoelectric Droplet Jet Technology in high volumes to accurate diameter uniformity, bright shiny surface finishes and high quality sphericity. Various diameters (0.76, 0.6, 0.5, 0.45, 0.3, 0.25, 0.1, 0.08, 0.07, 0.06 and 0.05 mm Dia.) are available at affordable low cost from 11 worldwide SHENMAO Technology locations.

SHENMAO High Drop-Resistance Alloy PF902-S (SAC0307X) greatly increases reliability and performance of Portable Electronic Devices drop test.

For 43 years, as the World's Major Solder Materials Provider, SHENMAO produces SMT Solder Paste, Wave Solder Bar, Solder Wire and Flux, Solder Preforms, LED Die Attach Paste, Laser Soldering Paste, Semiconductor Packaging Solder Spheres, Wafer Bumping Solder Paste, Dipping Flux and PV Ribbon.

For more information, please contact:

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e-mail: solder@shenmao.com

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